Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Collector Current	I_C	600	mA

Thermal Characteristics

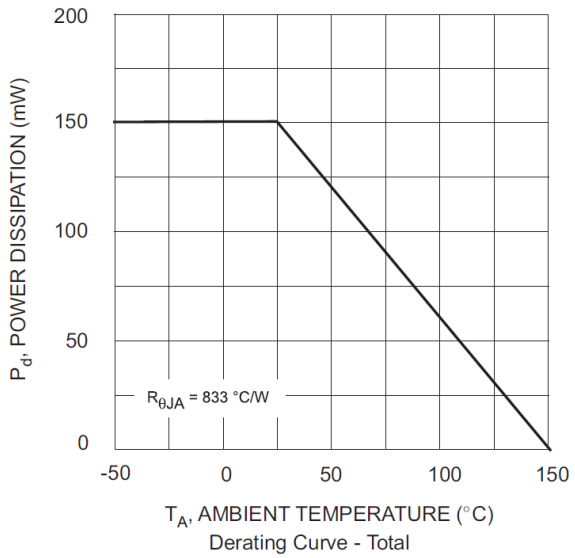
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	833	°C/W
Operating and Storage and Temperature Range	T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes: 5. For the device mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristic and Derating Information



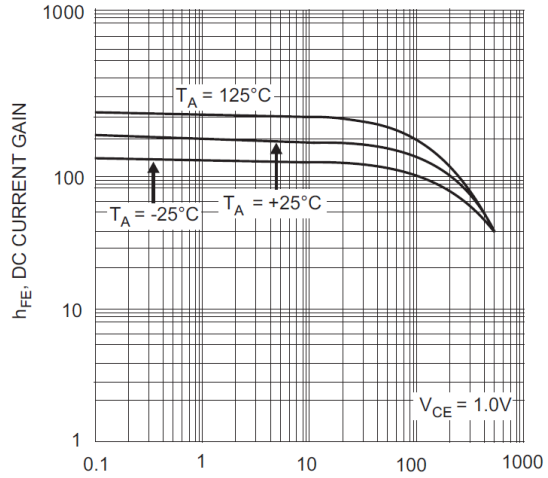
Derating Curve - Total

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

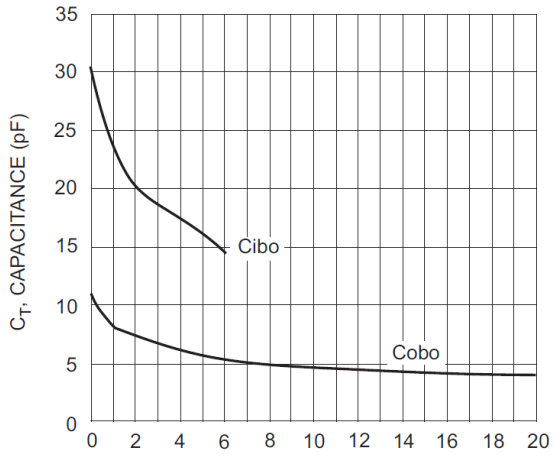
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS					
Collector-Base Breakdown Voltage	BV_{CBO}	75	—	V	I_C = 10µA, I_E = 0
Collector-Emitter Breakdown Voltage (Note 7)	BV_{CEO}	40	—	V	I_C = 10mA, I_B = 0
Emitter-Base Breakdown Voltage	BV_{EBO}	6.0	—	V	I_E = 100µA, I_C = 0
Collector-Base Cut-Off Current	I_{CBO}	—	10	nA µA	V_{CB} = 60V, I_E = 0 V_{CB} = 60V, I_E = 0, T_A = +150°C
Collector Cut-Off Current	I_{CEX}	—	10	nA	V_{CE} = 60V, $V_{BE(OFF)}$ = 3.0V
Emitter-Base Cut-Off Current	I_{EBO}	—	10	nA	V_{EB} = 3V, I_C = 0
Base Cut-Off Current	I_{BL}	—	20	nA	V_{CE} = 60V, $V_{BE(OFF)}$ = 3.0V
ON CHARACTERISTICS (Note 7)					
DC Current Gain	h_{FE}	35 50 75 100 40 50 35	— — — 300 — — —	—	I_C = 100µA, V_{CE} = 10V I_C = 1.0mA, V_{CE} = 10V I_C = 10mA, V_{CE} = 10V I_C = 150mA, V_{CE} = 10V I_C = 500mA, V_{CE} = 10V I_C = 10mA, V_{CE} = 10V, T_A = -55°C I_C = 150mA, V_{CE} = 1.0V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	0.3 1.0	V	I_C = 150mA, I_B = 15mA I_C = 500mA, I_B = 50mA
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	0.6 —	1.2 2.0	V	I_C = 150mA, I_B = 15mA I_C = 500mA, I_B = 50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C_{obo}	—	8.0	pF	V_{CB} = 10V, f = 1.0MHz, I_E = 0
Input Capacitance	C_{ibo}	—	25	pF	V_{EB} = 0.5V, f = 1.0MHz, I_C = 0
Current Gain-Bandwidth Product	f_T	300	—	MHz	V_{CE} = 20V, I_C = 20mA, f = 100MHz
Noise Figure	NF	—	4.0	dB	V_{CE} = 10V, I_C = 100µA, R_S = 1.0kΩ, f = 1.0kHz
SWITCHING CHARACTERISTICS					
Delay Time	t_d	—	10	ns	V_{CC} = 30V, I_C = 150mA, $V_{BE(off)}$ = - 0.5V, I_{B1} = 15mA
Rise Time	t_r	—	25	ns	
Storage Time	t_s	—	225	ns	V_{CC} = 30V, I_C = 150mA, I_{B1} = I_{B2} = 15mA
Fall Time	t_f	—	60	ns	

Note: 7. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.

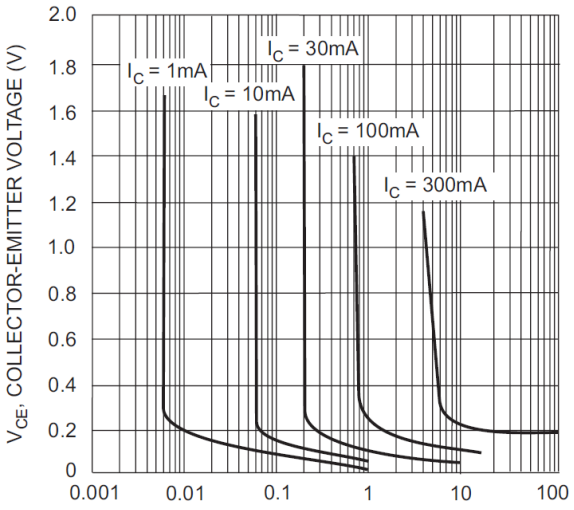
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



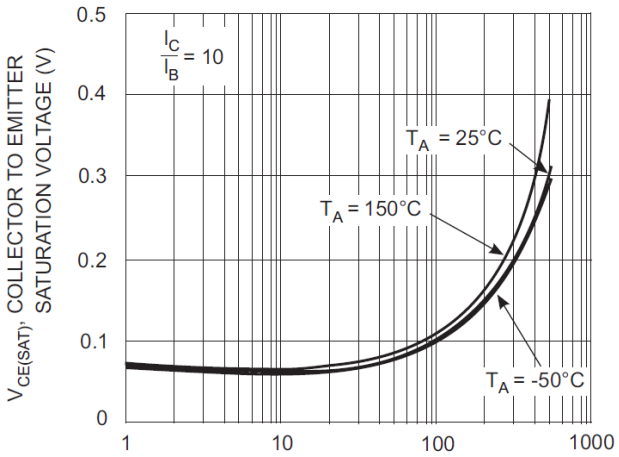
Typical DC Current Gain vs Collector Current



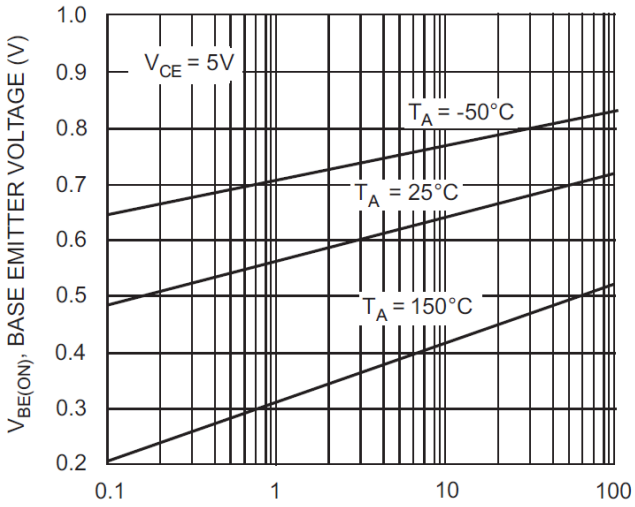
Typical Capacitance Characteristics



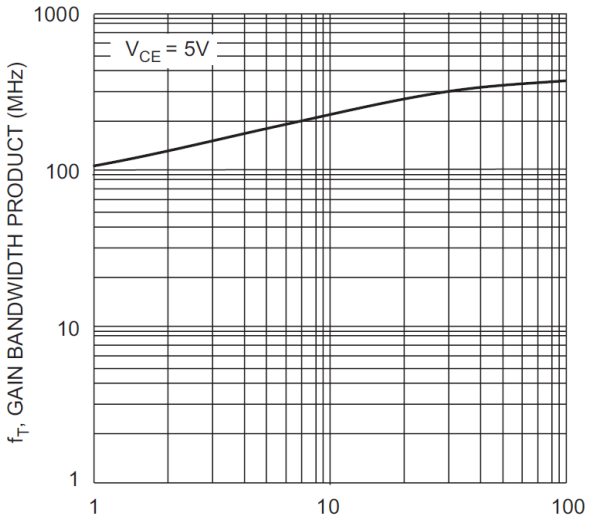
Typical Collector Saturation Region



Collector Emitter Saturation Voltage vs. Collector Current



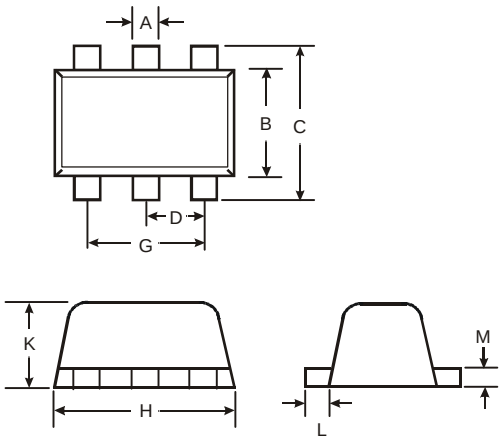
Base Emitter Voltage vs. Collector Current



Gain Bandwidth Product vs. Collector Current

Package Outline Dimensions

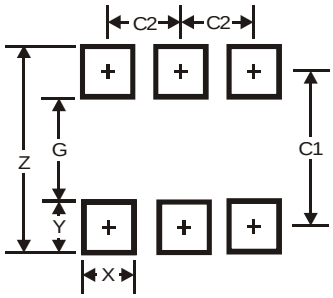
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT563			
Dim	**Min**	**Max**	**Typ**
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	SOT563
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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